

CLAIMS

What is claimed is:

1 1. A system for semiconductor manufacturing collaboration comprising:
2 at least one customer including a first collaboration application; and
3 at least one manufacturing partner including a second collaboration application;
4 wherein the first and second applications allow for peer-peer collaboration therebetween.

1 2. The system of claim 1 wherein each of the first and second applications provide
2 information to and receive information from their respective back office applications.

1 3. The system of claim 1 wherein the at least one manufacturing partner comprises
2 a plurality of manufacturing partners.
3

4 4. The system of claim 1 wherein work in progress (WIP) data is sent in a push
fashion from manufacturing partner to the customer.

1 5. The system of claim 1 wherein the first and second collaboration applications
2 include means for managing a project.

1 6. The system of claim 1 wherein the first and second collaboration applications

2 include means for document sharing.

1 7. The system of claim 1 wherein the first and second collaboration applications
2 include means for viewing work in progress (WIP) data.

1 8. The system of claim 1 wherein the first and second collaboration applications
2 includes means for providing reports.

1 9. The system of claim 1 wherein a chip manufacturing schedule can be sent to the
2 manufacturing partner.

1 10. The system of claim 1 wherein the first and second collaboration applications
2 include means for tracking issues.

1 11. The system of claim 1 wherein a lot status and progress of the semiconductor
2 produce lifecycle can be obtained in near real-time.

1 12. The system of claim 3 wherein the plurality of manufacturing partners send
2 engineering documents with revisions to the customer in an automated fashion.

1 13. The system of claim 3 wherein the customer sends documents to the plurality of
2 manufacturing partner with a project schedule.

1 14. The system of claim 1 wherein issues are managed collaboratively by the

applications.

15. The system of claim 3 wherein wafer maps, WAT reports, yield information are sent from the plurality of manufacturing partners to the customer.

16. The system of claim 1 wherein JAVA technology is utilized with the collaboration platforms.